

controlled coefficient of expansion and the resultant composite product. Three alternative techniques are used to first apply  
A, a hard solder in contact with a layer of fine particles between the two members. Then a final heating is applied under pressure to melt the hard solder. The resulting bonding layer bonds the two different fitting members.

IN THE SPECIFICATION:

Page 1, before line 5, insert the following new paragraph:

This is a Division of application Serial No. 09/603,203,  
US Patent No.

AZ filed June 26, 2000, now allowed.